





6-Pin DIP Zero-Cross **Optoisolators Triac Driver Output** (600 Volts Peak)

The MOC3162 and MOC3163 devices consist of gallium arsenide infrared emitting diodes optically coupled to monolithic silicon detectors performing the functions of Zero Voltage Crossing bilateral triac drivers.

They are designed for use with a triac in the interface of logic systems to equipment powered from 115/240 Vac lines, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances, etc.

- Simplifies Logic Control of 115/240 Vac Power
- Zero Voltage Turn-On
- dv/dt of 1000 V/μs Guaranteed Minimum @ 600 V Peak
- IFT Insensitive to Static dv/dt (Within Rated VDRM)
- To order devices that are tested and marked per VDE 0884 requirements, the suffix "V" must be included at end of part number. VDE 0884 is a test option.

Recommended for 115/240 Vac(rms) Applications:

- Solenoid/Valve Controls
- Lighting Controls
- Static Power Switches
- **AC Motor Drives**
- Static AC Power Switch

- Temperature Controls
- · E.M. Contactors
- AC Motor Starters
- Solid State Relays

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

| Rating | Symbol | Value | Unit | | |
|---|--------|-------------|-------------|--|--|
| INFRARED EMITTING DIODE | | | | | |
| Reverse Voltage | ٧R | 6.0 | Volts | | |
| Forward Current — Continuous | ΙF | 60 | mA | | |
| Total Power Dissipation @ T _A = 25°C Negligible Power in Output Driver Derate above 25°C | PD | 120 1.60 | mW mW/°C | | |
| OUTPUT DRIVER | | | | | |

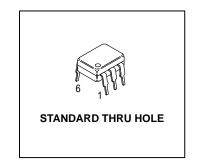
| Off-State Output Terminal Voltage | V_{DRM} | 600 | Volts | |
|--|----------------|------------|-------------|--|
| Peak Repetitive Surge Current (PW = 100 μs, 120 pps) | ITSM | 1.0 | А | |
| Total Power Dissipation @ T _A = 25°C Derate above 25°C | P _D | 150 2.0 | mW mW/°C | |

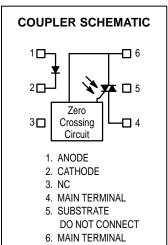
TOTAL DEVICE

| Isolation Surge Voltage (1) (Peak ac Voltage, 60 Hz, 1 Second Duration) | VISO | 7500 | Vac(pk) |
|---|------------------|-------------|-------------|
| Total Power Dissipation @ T _A = 25°C Derate above 25°C | PD | 250 3.3 | mW mW/°C |
| Junction Temperature Range | TJ | -40 to +100 | °C |
| Ambient Operating Temperature Range | TA | -40 to +85 | °C |
| Storage Temperature Range | T _{stg} | -40 to +150 | °C |
| Soldering Temperature (10 s) | TL | 260 | °C |

^{1.} Isolation surge voltage, VISO, is an internal device dielectric breakdown rating. For this test, Pins 1 and 2 are common, and Pins 4, 5 and 6 are common.

MOC3162 MOC3163







ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Тур | Max | Unit |
|--|-------------------|------|------|-----------|-------|
| INPUT LED | • | • | | | |
| Reverse Leakage Current (V _R = 6.0 V) | I _R | _ | 0.05 | 100 | μА |
| Forward Voltage (IF = 30 mA) | VF | _ | 1.15 | 1.5 | Volts |
| OUTPUT DETECTOR (I _F = 0) | • | • | | | |
| Leakage with LED Off, Either Direction (Rated V _{DRM} , Note 1) | IDRM | _ | 10 | 100 | nA |
| Critical Rate of Rise of Off–State Voltage (Note 3) @ 600 V Peak | dv/dt | 1000 | _ | _ | V/μs |
| COUPLED | • | | | | • |
| LED Trigger Current, Current Required to Latch Output (Main Terminal Voltage = 3.0 V, Note 2) MOC3162 MOC3163 | lFT | _ | | 10 5.0 | mA |
| Peak On–State Voltage, Either Direction (I _{TM} = 100 mA Peak, I _F = Rated I _{FT}) | V _{TM} | _ | 1.7 | 3.0 | Volts |
| Holding Current, Either Direction | lн | _ | 200 | _ | μΑ |
| Inhibit Voltage (MT1–MT2 Voltage Above Which Device Will Not Trigger) (IF = Rated IFT) | VINH | _ | 8.0 | 15 | Volts |
| Leakage in Inhibited State (IF = 10 mA Maximum, at Rated V _{DRM} , Off State) | I _{DRM2} | _ | 250 | 500 | μА |

- 1. Test voltage must be applied within dv/dt rating.
- 2. All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT}. Therefore, recommended operating I_F lies between max I_{FT} (10 mA for MOC3162, 5.0 mA for MOC3163) and absolute max I_F (60 mA).
- 3. This is static dv/dt. See Figure 9 for test circuit. Commutating dv/dt is a function of the load–driving thyristor(s) only.

TYPICAL ELECTRICAL CHARACTERISTICS



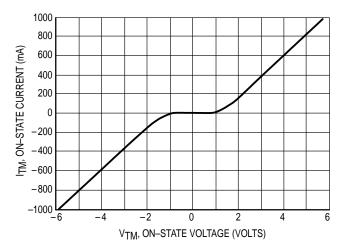


Figure 1. On-State Characteristics

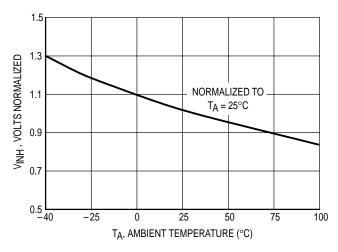


Figure 2. Inhibit Voltage versus Temperature



TYPICAL ELECTRICAL CHARACTERISTICS



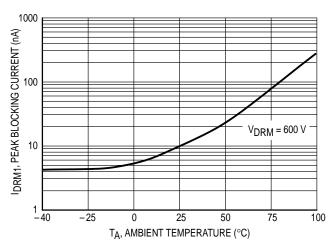


Figure 3. Leakage with LED Off versus Temperature

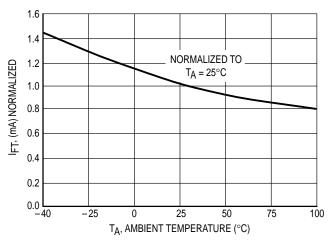


Figure 5. Trigger Current versus Temperature

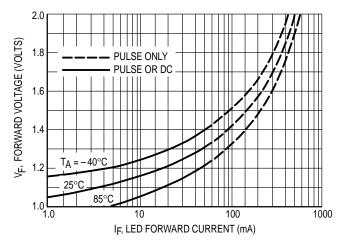


Figure 6. LED Forward Voltage versus Forward Current

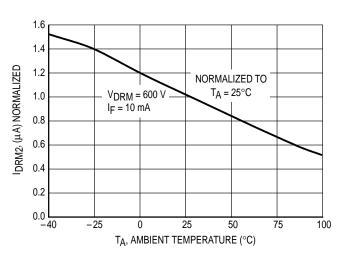


Figure 4. IDRM2, Leakage in Inhibit State versus Temperature

IFT versus Temperature (Normalized)

This graph shows the increase of the trigger current when the device is expected to operate at an ambient temperature below 25°C. Multiply the normalized IFT shown on this graph with the data sheet guaranteed IFT.

Example

$$T_A = -40$$
°C, $I_{FT} = 10$ mA
 $I_{FT} @ -40$ °C = 10 mA x 1.4 = 14 mA

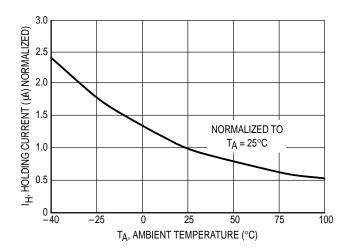


Figure 7. Holding Current, IH versus Temperature



TYPICAL ELECTRICAL CHARACTERISTICS

$T_A = 25^{\circ}C$

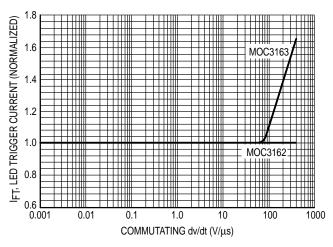


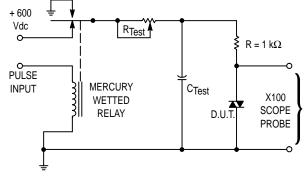
Figure 8. LED Trigger Current, IFT, versus dv/dt

IFT versus dv/dt

Triac drivers with good noise immunity (dv/dt stat.) have internal noise rejection circuits which prevent false triggering of the device in the event of fast raising line voltage transients. Inductive loads generate a commutating dv/dt that may activate the triac driver's noise suppression circuits. This prevents the device from turning on at its specified trigger current. It will in this case go into the mode of "half-waving" of the load. Half-waving of the load may destroy the power triac and the load.

Figure 8 shows the dependency of the triac drivers IFT versus the reapplied voltage rise with a $\rm V_{p}$ of 600 V. This dv/dt condition simulates a worst case commutating dv/dt amplitude.

It can be seen that the required trigger current IFT changes with increased dv/dt. Practical loads generate a commutating dv/dt of less than 50 V/ μ s. The rate of rise of the commutating dv/dt is effectively slowed by the use of snubber networks across the main triac. This snubber is also needed to keep the commutating dv/dt generated by inductive loads within the commutating dv/dt ratings of the power triac.



- 1. The mercury wetted relay provides a high speed repeated pulse to the D.U.T.
- 2. 100x scope probes are used, to allow high speeds and voltages.
- 3. The worst–case condition for static dv/dt is established by triggering the D.U.T. with a normal LED input current, then removing the current. The variable RTEST allows the dv/dt to be gradually increased until the D.U.T. continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the D.U.T. stops triggering. TRC is measured at this point and recorded.

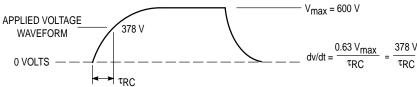


Figure 9. Static dv/dt Test Circuit



TYPICAL ELECTRICAL CHARACTERISTICS

 $T_A = 25^{\circ}C$

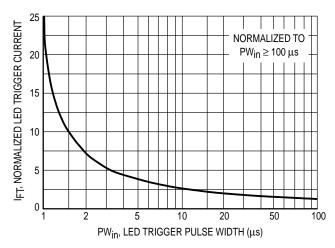


Figure 10. LED Current Required to Trigger versus LED Pulse Width

LED Trigger Current versus PW (Normalized)

For resistive loads the triac drivers may be controlled by short pulse into the input LED. This input pulse must be synchronized with the AC line voltage zero—crossing points. LED trigger pulse currents shorter than 100 μ s must have an increased amplitude as shown on Figure 10. This graph shows the dependency of the trigger current IFT versus the pulse width t(PW). IFT in the graph, IFT versus (PW), is normalized in respect to the minimum specified IFT for static condition, which is specified in the device characteristic. The normalized IFT has to be multiplied with the device's guaranteed static trigger current.

Example:

Guaranteed IFT = 10 mA, Trigger pulse width PW = $3.0~\mu s$ IFT(pulsed) = 10~mA~x~5.0 = 50~mA



APPLICATIONS GUIDE

BASIC APPLICATIONS

Basic Triac Driver Circuit

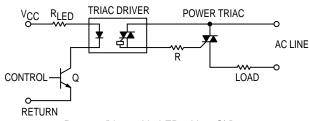
Zero-cross triac drivers are very immune to static dv/dt. This allows snubberless operations in all applications where the external generated noise amplitude and rate of rise in the AC line is not exceeding the devices' guaranteed limits. For these applications a snubber circuit is not necessary when a noise insensitive power triac is used. Figure 11 shows the circuit diagram. The triac driver is directly connected to the triac main terminal 2 and a series Resistor R which limits the current to the triac driver. Current limiting resistor R could be very small for normal operation since the triac driver can be only switched on within the zero-cross window. Worst case consideration, however, considers accidental turn on at the peak of the line voltage due to a line transient exceeding the devices' maximum ratings. For this reason R should be calculated to limit the current to Idrm max at the peak of the line voltage.

$$R = V_D AC/I_{TM} max rep. = V_D AC/1A$$

The power dissipation of this current limiting resistor and the triac driver is very small because the power triac carries the load current as soon as the current through driver and current limiting resistor reaches the trigger current of the power triac. The switching transition time for the driver is only one micro second and for power triacs typical four micro seconds.

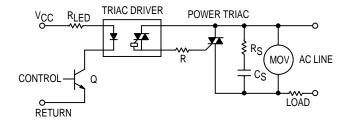
Triac Driver Circuit for Noisy Environments

When the transient rate of rise and amplitude are expected to exceed the power triacs and triac drivers maximum ratings a snubber circuit as shown in Figure 12 is recommended. Fast transients are slowed by the R–C snubber and excessive amplitudes are clipped by the Metal Oxide Varistor MOV.



RLED = (VCC - VF LED - V_{sat} Q)/IFT R = V_p AC line/I_{TSM} The load may be placed on either side of the AC line.

Figure 11. Basic Driver Circuit



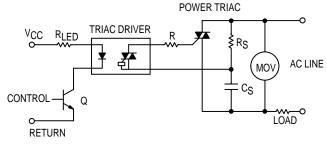
Traditional snubber configuration Typical Snubber values RS = 33 Ω , CS = 0.01 μ F MOV (Metal Oxide Varistor) protects triac and driver from transient overvoltages >VDRM max

Figure 12. Triac Driver Circuit for Noisy Environments

Triac Driver Circuit for Extremely Noisy Environments

Noisy environments for this circuit are defined in the noise standards IEEE472, IEC255–4 and IEC801–4.

Industrial control applications, for example, do specify a maximum expected transient noise dv/dt and peak voltage which is superimposed onto the AC line voltage. Figure 13 shows a split snubber network which enhances the circuits noise immunity by protecting the triac driver with optimized efficiency.



Recommended snubber values R_S = 10 W, C_S = 0.033 mF

Figure 13. Triac Driver Circuit for Extremely Noisy Environments



APPLICATIONS GUIDE

Hot-Line Switching Application Circuit

Typical circuit for use when hot–line switching is required. In this circuit the "hot" side of the line is switched and the load connected to the cold or neutral side. The load may be connected to either the neutral or hot–line.

 $R_{\mbox{\scriptsize in}}$ is calculated so that IF is equal to the rated IFT of the part, 10 mA for the MOC3162, and 5.0 mA for the MOC3163. The 39 ohm resistor and 0.01 $\mu\mbox{\scriptsize F}$ capacitor are for snubbing of the triac and may or may not be necessary depending upon the particular triac and load used.

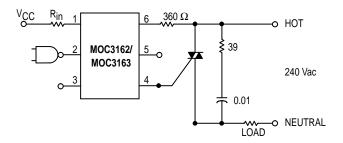


Figure 14. Hot-Line Switching Application Circuit

Inverse Parallel SCR Driver Circuit

Two inverse parallel SCR's are controlled by one triac driver with a minimum component count as shown in Figure 15. A snubber network and a MOV across the main terminals of the SCR's protects the semiconductors from transients on the AC line.

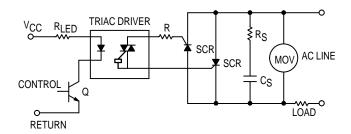
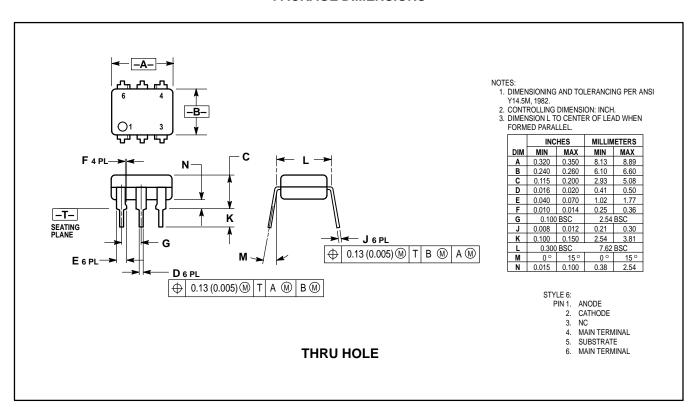
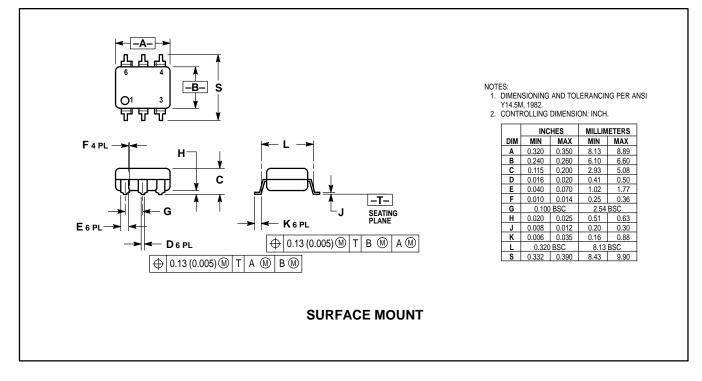


Figure 15. Inverse Parallel SCR Driver Circuit



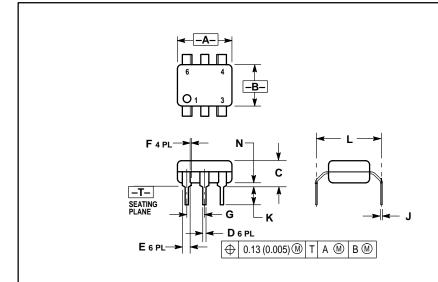
PACKAGE DIMENSIONS











- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

| | INCHES | | MILLIMETERS | | |
|-----|-----------|-------|-------------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.320 | 0.350 | 8.13 | 8.89 | |
| В | 0.240 | 0.260 | 6.10 | 6.60 | |
| C | 0.115 | 0.200 | 2.93 | 5.08 | |
| D | 0.016 | 0.020 | 0.41 | 0.50 | |
| Е | 0.040 | 0.070 | 1.02 | 1.77 | |
| F | 0.010 | 0.014 | 0.25 | 0.36 | |
| G | 0.100 BSC | | 2.54 BSC | | |
| 7 | 0.008 | 0.012 | 0.21 | 0.30 | |
| K | 0.100 | 0.150 | 2.54 | 3.81 | |
| L | 0.400 | 0.425 | 10.16 | 10.80 | |
| N | 0.015 | 0.040 | 0.38 | 1.02 | |

0.4" LEAD SPACING



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